

Cluj-Napoca welcomes SIITME Conference 2019!



We are honoured and pleased to organize the next edition of the SIITME conference, an anniversary one, in Cluj-Napoca. The twenty-five years that our conference celebrates next year go well with the young and academic spirit of our city.

The excellence that is usually promoted by SIITME will fit well with the scientific and cultural life of Cluj-Napoca. During 2019, our city will continue to see, each week, new national and international events.

We are convinced that the next edition of our conference will attract a large number of participants from academia and the industry. The innovative spirit of the conference certifies that we will have, among us, representatives of top areas of cutting-edge technologies promoted in our city and region.



Autumn is the most beautiful season in Cluj-Napoca and we invite you to see it for yourselves in October 2019!



SIITME 2019

See you in Cluj!





SIITME 2019

IEEE 25th International Symposium for Design and Technology in Electronics Packaging



Call for Papers

The organising committee of SIITME 2019 kindly invites you to submit an abstract/paper to the 2019 IEEE 25th International Symposium for Design and Technology in Electronics Packaging (SIITME).

Topics

- Emerging technologies in advanced packaging;
- Components, assembling and manufacturing technology;
- Embedded systems, aerospace, robotics and artificial intelligence;
- Power electronics, thermal management,
- Smart grid, renewable energy;
- Virtual prototyping and System validation;
- Applied reliability, characterization and testing, failure diagnostic;
- Challenges in global education;

www.sitme.ro

Venue

Cluj-Napoca, Romania
October 23rd – 26th 2019



Calendar

Submission of abstracts:

20th of May 2019

Abstract acceptance:

30th of June 2019

Submission of papers:

1st of September 2019

Authors registration deadline:

20th of September 2019

Participants registration deadline:

10th of October 2019